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FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

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APPLICANT: Herbert J. Neuhaus et al.		
FILING DATE 19 March 2001	GROUP 2826	

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	NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.